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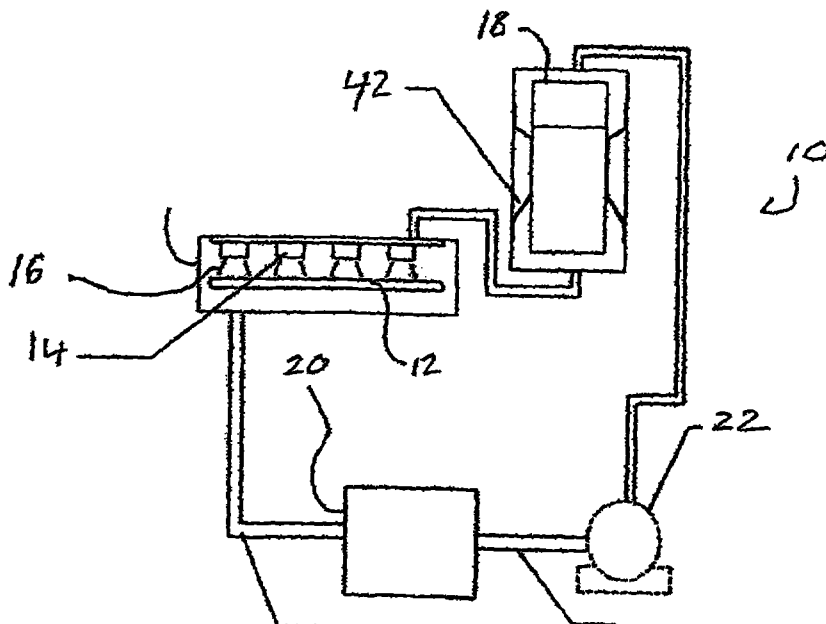
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(54) Title: SPRAY COOLING SYSTEM



(57) Abstract: A spray cooling system for semiconductor devices. An ink-jet type spray device sprays droplets of a cooling fluid onto the semiconductor devices. The devices vaporize the liquid, which gets passed through a roll bond panel, or other heat exchanger, and is pumped into a spring loaded reservoir that feeds the spray device.



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